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### Understanding **Embedded - FPGAs (Field Programmable Gate Array)**

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

### Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications,

#### Details

Product Status	Active
Number of LABs/CLBs	1139
Number of Logic Elements/Cells	14579
Total RAM Bits	589824
Number of I/O	160
Number of Gates	-
Voltage - Supply	1.14V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	225-LFBGA, CSPBGA
Supplier Device Package	225-CSPBGA (13x13)
Purchase URL	<a href="https://www.e-xfl.com/product-detail/xilinx/xc6slx16-3csg225i">https://www.e-xfl.com/product-detail/xilinx/xc6slx16-3csg225i</a>

Table 1: Absolute Maximum Ratings<sup>(1)</sup> (Cont'd)

Symbol	Description				Units	
$V_{IN}$ and $V_{TS}$ <sup>(3)</sup>	I/O input voltage or voltage applied to 3-state output, relative to GND <sup>(4)</sup>	All user and dedicated I/Os	Commercial	DC	-0.60 to 4.10	V
				20% overshoot duration	-0.75 to 4.25	V
				8% overshoot duration <sup>(5)</sup>	-0.75 to 4.40	V
			Industrial	DC	-0.60 to 3.95	V
				20% overshoot duration	-0.75 to 4.15	V
				4% overshoot duration <sup>(5)</sup>	-0.75 to 4.40	V
			Expanded (Q)	DC	-0.60 to 3.95	V
				20% overshoot duration	-0.75 to 4.15	V
				4% overshoot duration <sup>(5)</sup>	-0.75 to 4.40	V
		Restricted to maximum of 100 user I/Os	Commercial	20% overshoot duration	-0.75 to 4.35	V
				15% overshoot duration <sup>(5)</sup>	-0.75 to 4.40	V
				10% overshoot duration	-0.75 to 4.45	V
			Industrial	20% overshoot duration	-0.75 to 4.25	V
				10% overshoot duration	-0.75 to 4.35	V
				8% overshoot duration <sup>(5)</sup>	-0.75 to 4.40	V
Expanded (Q)	20% overshoot duration	-0.75 to 4.25	V			
	10% overshoot duration	-0.75 to 4.35	V			
	8% overshoot duration <sup>(5)</sup>	-0.75 to 4.40	V			
$T_{STG}$	Storage temperature (ambient)				-65 to 150 °C	
$T_{SOL}$	Maximum soldering temperature <sup>(6)</sup> (TQG144, CPG196, CSG225, CSG324, CSG484, and FTG256)				+260 °C	
	Maximum soldering temperature <sup>(6)</sup> (Pb-free packages: FGG484, FGG676, and FGG900)				+250 °C	
	Maximum soldering temperature <sup>(6)</sup> (Pb packages: CS484, FT256, FG484, FG676, and FG900)				+220 °C	
$T_j$	Maximum junction temperature <sup>(6)</sup>				+125 °C	

**Notes:**

1. Stresses beyond those listed under Absolute Maximum Ratings might cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those listed under Operating Conditions is not implied. Exposure to Absolute Maximum Ratings conditions for extended periods of time might affect device reliability.
2. When programming eFUSE,  $V_{FS} \leq V_{CCAUX}$ . Requires up to 40 mA current. For read mode,  $V_{FS}$  can be between GND and 3.45 V.
3. I/O absolute maximum limit applied to DC and AC signals. Overshoot duration is the percentage of a data period that the I/O is stressed beyond 3.45V.
4. For I/O operation, refer to [UG381](#): *Spartan-6 FPGA SelectIO Resources User Guide*.
5. Maximum percent overshoot duration to meet 4.40V maximum.
6. For soldering guidelines and thermal considerations, see [UG385](#): *Spartan-6 FPGA Packaging and Pinout Specification*.

Table 3: eFUSE Programming Conditions<sup>(1)</sup>

Symbol	Description	Min	Typ	Max	Units
$V_{FS}$ <sup>(2)</sup>	External voltage supply	3.2	3.3	3.4	V
$I_{FS}$	$V_{FS}$ supply current	–	–	40	mA
$V_{CCAUX}$	Auxiliary supply voltage relative to GND	3.2	3.3	3.45	V
$R_{FUSE}$ <sup>(3)</sup>	External resistor from $R_{FUSE}$ pin to GND	1129	1140	1151	$\Omega$
$V_{CCINT}$	Internal supply voltage relative to GND	1.14	1.2	1.26	V
$t_j$	Temperature range	15	–	85	$^{\circ}\text{C}$

**Notes:**

1. These specifications apply during programming of the eFUSE AES key. Programming is only supported through JTAG. The AES key is only supported in the following devices: LX75, LX75T, LX100, LX100T, LX150, and LX150T.
2. When programming eFUSE,  $V_{FS}$  must be less than or equal to  $V_{CCAUX}$ . When not programming or when eFUSE is not used, Xilinx recommends connecting  $V_{FS}$  to GND. However,  $V_{FS}$  can be between GND and 3.45 V.
3. An  $R_{FUSE}$  resistor is required when programming the eFUSE AES key. When not programming or when eFUSE is not used, Xilinx recommends connecting the  $R_{FUSE}$  pin to  $V_{CCAUX}$  or GND. However,  $R_{FUSE}$  can be unconnected.

## GTP Transceiver DC Input and Output Levels

Table 16 summarizes the DC output specifications of the GTP transceivers in Spartan-6 FPGAs. Figure 1 shows the single-ended output voltage swing. Figure 2 shows the peak-to-peak differential output voltage.

Consult UG386: *Spartan-6 FPGA GTP Transceivers User Guide* for further details.

Table 16: GTP Transceiver DC Specifications

Symbol	DC Parameter	Conditions	Min	Typ	Max	Units
DV <sub>PPIN</sub>	Differential peak-to-peak input voltage	External AC coupled	140	–	2000	mV
V <sub>IN</sub>	Absolute input voltage	DC coupled MGTAVTTRX = 1.2V	–400	–	MGTAVTTRX	mV
V <sub>CMIN</sub>	Common mode input voltage	DC coupled MGTAVTTRX = 1.2V	–	3/4 MGTAVTTRX	–	mV
DV <sub>PPOUT</sub>	Differential peak-to-peak output voltage <sup>(1)</sup>	Transmitter output swing is set to maximum setting	–	–	1000	mV
V <sub>SEOUT</sub>	Single-ended output voltage swing <sup>(1)</sup>		–	–	500	mV
V <sub>CMOUTDC</sub>	Common mode output voltage	Equation based	MGTAVTTTX – V <sub>SEOUT</sub> /2			mV
R <sub>IN</sub>	Differential input resistance		80	100	130	Ω
R <sub>OUT</sub>	Differential output resistance		80	100	130	Ω
T <sub>OSKEW</sub>	Transmitter output skew		–	–	15	ps
C <sub>EXT</sub>	Recommended external AC coupling capacitor <sup>(2)</sup>		75	100	200	nF

**Notes:**

1. The output swing and preemphasis levels are programmable using the attributes discussed in UG386: *Spartan-6 FPGA GTP Transceivers User Guide* and can result in values lower than reported in this table.
2. Other values can be used as appropriate to conform to specific protocols and standards.

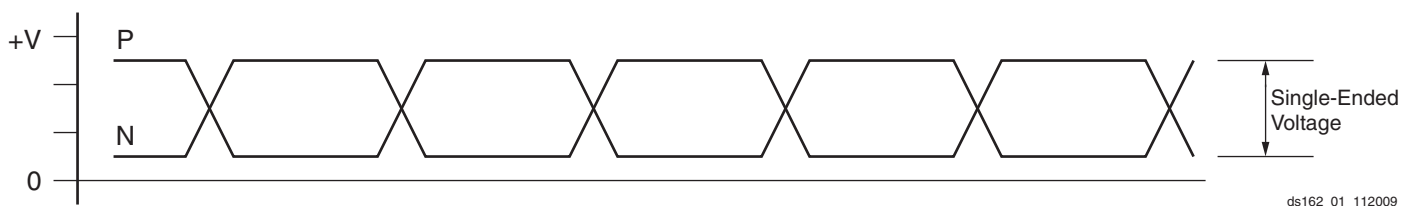


Figure 1: Single-Ended Peak-to-Peak Voltage

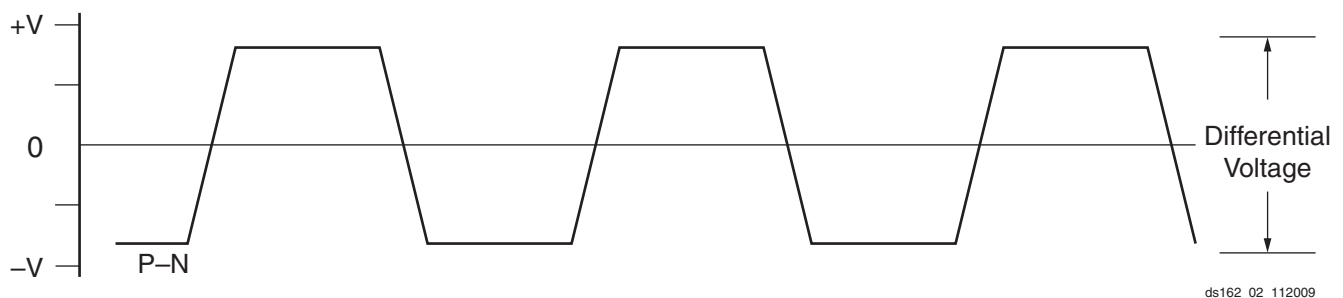


Figure 2: Differential Peak-to-Peak Voltage

Table 17 summarizes the DC specifications of the clock input of the GTP transceiver. Consult UG386: *Spartan-6 FPGA GTP Transceivers User Guide* for further details.

Table 28: IOB Switching Characteristics for the Commercial (XC) Spartan-6 Devices (Cont'd)

I/O Standard	T <sub>IOPI</sub>				T <sub>IOOP</sub>				T <sub>IOTP</sub>				Units
	Speed Grade				Speed Grade				Speed Grade				
	-3	-3N	-2	-1L <sup>(1)</sup>	-3	-3N	-2	-1L <sup>(1)</sup>	-3	-3N	-2	-1L <sup>(1)</sup>	
PPDS_33	1.17	1.29	1.42	1.68	1.57	1.71	1.91	2.43	3000	3000	3000	3000	ns
PPDS_25	1.01	1.13	1.26	1.56	1.68	1.82	2.02	2.47	3000	3000	3000	3000	ns
PCI33_3	1.07	1.19	1.32	1.57 <sup>(2)</sup>	3.51	3.65	3.85	4.38 <sup>(2)</sup>	3.51	3.65	3.85	4.38 <sup>(1)</sup>	ns
PCI66_3	1.07	1.19	1.32	1.57 <sup>(2)</sup>	3.53	3.67	3.87	4.39 <sup>(2)</sup>	3.53	3.67	3.87	4.39 <sup>(1)</sup>	ns
DISPLAY_PORT	1.02	1.14	1.27	1.56	3.15	3.29	3.49	4.08	3.15	3.29	3.49	4.08	ns
I2C	1.33	1.45	1.58	1.82	11.56	11.70	11.90	12.52	11.56	11.70	11.90	12.52	ns
SMBUS	1.33	1.45	1.58	1.82	11.56	11.70	11.90	12.52	11.56	11.70	11.90	12.52	ns
SDIO	1.36	1.48	1.61	1.84	2.64	2.78	2.98	3.60	2.64	2.78	2.98	3.60	ns
MOBILE_DDR	0.94	1.06	1.19	1.43	2.35	2.49	2.69	3.31	2.35	2.49	2.69	3.31	ns
HSTL_I	0.90	1.02	1.15	1.39	1.66	1.80	2.00	2.62	1.66	1.80	2.00	2.62	ns
HSTL_II	0.91	1.03	1.16	1.40	1.72	1.86	2.06	2.68	1.72	1.86	2.06	2.68	ns
HSTL_III	0.95	1.07	1.20	1.44	1.67	1.81	2.01	2.61	1.67	1.81	2.01	2.61	ns
HSTL_I_18	0.94	1.06	1.19	1.43	1.77	1.91	2.11	2.73	1.77	1.91	2.11	2.73	ns
HSTL_II_18	0.94	1.06	1.19	1.43	1.85	1.99	2.19	2.81	1.85	1.99	2.19	2.81	ns
HSTL_III_18	0.99	1.11	1.24	1.47	1.79	1.93	2.13	2.72	1.79	1.93	2.13	2.72	ns
SSTL3_I	1.58	1.70	1.83	2.16	1.83	1.97	2.17	2.72	1.83	1.97	2.17	2.72	ns
SSTL3_II	1.58	1.70	1.83	2.16	2.01	2.15	2.35	2.94	2.01	2.15	2.35	2.94	ns
SSTL2_I	1.30	1.42	1.55	1.87	1.77	1.91	2.11	2.69	1.77	1.91	2.11	2.69	ns
SSTL2_II	1.30	1.42	1.55	1.88	1.86	2.00	2.20	2.82	1.86	2.00	2.20	2.82	ns
SSTL18_I	0.92	1.04	1.17	1.41	1.63	1.77	1.97	2.59	1.63	1.77	1.97	2.59	ns
SSTL18_II	0.92	1.04	1.17	1.41	1.66	1.80	2.00	2.62	1.66	1.80	2.00	2.62	ns
SSTL15_II	0.92	1.04	1.17	1.41	1.67	1.81	2.01	2.63	1.67	1.81	2.01	2.63	ns
DIFF_HSTL_I	0.94	1.06	1.19	1.46	1.77	1.91	2.11	2.62	1.77	1.91	2.11	2.62	ns
DIFF_HSTL_II	0.93	1.05	1.18	1.45	1.72	1.86	2.06	2.54	1.72	1.86	2.06	2.54	ns
DIFF_HSTL_III	0.93	1.05	1.18	1.46	1.69	1.83	2.03	2.53	1.69	1.83	2.03	2.53	ns
DIFF_HSTL_I_18	0.97	1.09	1.22	1.50	1.79	1.93	2.13	2.63	1.79	1.93	2.13	2.63	ns
DIFF_HSTL_II_18	0.97	1.09	1.22	1.49	1.69	1.83	2.03	2.51	1.69	1.83	2.03	2.51	ns
DIFF_HSTL_III_18	0.97	1.09	1.22	1.50	1.69	1.83	2.03	2.53	1.69	1.83	2.03	2.53	ns
DIFF_SSTL3_I	1.18	1.30	1.43	1.68	1.81	1.95	2.15	2.64	1.81	1.95	2.15	2.64	ns
DIFF_SSTL3_II	1.19	1.31	1.44	1.68	1.80	1.94	2.14	2.63	1.80	1.94	2.14	2.63	ns
DIFF_SSTL2_I	1.02	1.14	1.27	1.57	1.80	1.94	2.14	2.62	1.80	1.94	2.14	2.62	ns
DIFF_SSTL2_II	1.02	1.14	1.27	1.57	1.76	1.90	2.10	2.57	1.76	1.90	2.10	2.57	ns
DIFF_SSTL18_I	0.97	1.09	1.22	1.51	1.72	1.86	2.06	2.56	1.72	1.86	2.06	2.56	ns
DIFF_SSTL18_II	0.98	1.10	1.23	1.50	1.68	1.82	2.02	2.52	1.68	1.82	2.02	2.52	ns
DIFF_SSTL15_II	0.94	1.06	1.19	1.46	1.67	1.81	2.01	2.50	1.67	1.81	2.01	2.50	ns
DIFF_MOBILE_DDR	0.97	1.09	1.22	1.51	1.75	1.89	2.09	2.57	1.75	1.89	2.09	2.57	ns

Table 28: IOB Switching Characteristics for the Commercial (XC) Spartan-6 Devices (Cont'd)

I/O Standard	T <sub>IOPI</sub>				T <sub>IOOP</sub>				T <sub>IOTP</sub>				Units
	Speed Grade				Speed Grade				Speed Grade				
	-3	-3N	-2	-1L <sup>(1)</sup>	-3	-3N	-2	-1L <sup>(1)</sup>	-3	-3N	-2	-1L <sup>(1)</sup>	
LVC MOS18, Slow, 24 mA	1.18	1.30	1.43	2.04	1.99	2.13	2.33	2.95	1.99	2.13	2.33	2.95	ns
LVC MOS18, Fast, 2 mA	1.18	1.30	1.43	2.04	3.59	3.73	3.93	4.53	3.59	3.73	3.93	4.53	ns
LVC MOS18, Fast, 4 mA	1.18	1.30	1.43	2.04	2.39	2.53	2.73	3.35	2.39	2.53	2.73	3.35	ns
LVC MOS18, Fast, 6 mA	1.18	1.30	1.43	2.04	1.88	2.02	2.22	2.84	1.88	2.02	2.22	2.84	ns
LVC MOS18, Fast, 8 mA	1.18	1.30	1.43	2.04	1.81	1.95	2.15	2.77	1.81	1.95	2.15	2.77	ns
LVC MOS18, Fast, 12 mA	1.18	1.30	1.43	2.04	1.71	1.85	2.05	2.67	1.71	1.85	2.05	2.67	ns
LVC MOS18, Fast, 16 mA	1.18	1.30	1.43	2.04	1.71	1.85	2.05	2.67	1.71	1.85	2.05	2.67	ns
LVC MOS18, Fast, 24 mA	1.18	1.30	1.43	2.04	1.71	1.85	2.05	2.67	1.71	1.85	2.05	2.67	ns
LVC MOS18_JEDEC, QUIETIO, 2 mA	0.94	1.06	1.19	1.41	5.91	6.05	6.25	6.79	5.91	6.05	6.25	6.79	ns
LVC MOS18_JEDEC, QUIETIO, 4 mA	0.94	1.06	1.19	1.41	4.75	4.89	5.09	5.64	4.75	4.89	5.09	5.64	ns
LVC MOS18_JEDEC, QUIETIO, 6 mA	0.94	1.06	1.19	1.41	4.04	4.18	4.38	4.96	4.04	4.18	4.38	4.96	ns
LVC MOS18_JEDEC, QUIETIO, 8 mA	0.94	1.06	1.19	1.41	3.71	3.85	4.05	4.62	3.71	3.85	4.05	4.62	ns
LVC MOS18_JEDEC, QUIETIO, 12 mA	0.94	1.06	1.19	1.41	3.35	3.49	3.69	4.28	3.35	3.49	3.69	4.28	ns
LVC MOS18_JEDEC, QUIETIO, 16 mA	0.94	1.06	1.19	1.41	3.20	3.34	3.54	4.13	3.20	3.34	3.54	4.13	ns
LVC MOS18_JEDEC, QUIETIO, 24 mA	0.94	1.06	1.19	1.41	2.96	3.10	3.30	3.98	2.96	3.10	3.30	3.98	ns
LVC MOS18_JEDEC, Slow, 2 mA	0.94	1.06	1.19	1.41	4.59	4.73	4.93	5.54	4.59	4.73	4.93	5.54	ns
LVC MOS18_JEDEC, Slow, 4 mA	0.94	1.06	1.19	1.41	3.69	3.83	4.03	4.60	3.69	3.83	4.03	4.60	ns
LVC MOS18_JEDEC, Slow, 6 mA	0.94	1.06	1.19	1.41	3.00	3.14	3.34	3.94	3.00	3.14	3.34	3.94	ns
LVC MOS18_JEDEC, Slow, 8 mA	0.94	1.06	1.19	1.41	2.19	2.33	2.53	3.18	2.19	2.33	2.53	3.18	ns
LVC MOS18_JEDEC, Slow, 12 mA	0.94	1.06	1.19	1.41	1.99	2.13	2.33	2.95	1.99	2.13	2.33	2.95	ns
LVC MOS18_JEDEC, Slow, 16 mA	0.94	1.06	1.19	1.41	1.99	2.13	2.33	2.95	1.99	2.13	2.33	2.95	ns
LVC MOS18_JEDEC, Slow, 24 mA	0.94	1.06	1.19	1.41	1.99	2.13	2.33	2.95	1.99	2.13	2.33	2.95	ns
LVC MOS18_JEDEC, Fast, 2 mA	0.94	1.06	1.19	1.41	3.57	3.71	3.91	4.52	3.57	3.71	3.91	4.52	ns
LVC MOS18_JEDEC, Fast, 4 mA	0.94	1.06	1.19	1.41	2.39	2.53	2.73	3.35	2.39	2.53	2.73	3.35	ns
LVC MOS18_JEDEC, Fast, 6 mA	0.94	1.06	1.19	1.41	1.88	2.02	2.22	2.84	1.88	2.02	2.22	2.84	ns
LVC MOS18_JEDEC, Fast, 8 mA	0.94	1.06	1.19	1.41	1.80	1.94	2.14	2.76	1.80	1.94	2.14	2.76	ns
LVC MOS18_JEDEC, Fast, 12 mA	0.94	1.06	1.19	1.41	1.72	1.86	2.06	2.68	1.72	1.86	2.06	2.68	ns
LVC MOS18_JEDEC, Fast, 16 mA	0.94	1.06	1.19	1.41	1.72	1.86	2.06	2.68	1.72	1.86	2.06	2.68	ns
LVC MOS18_JEDEC, Fast, 24 mA	0.94	1.06	1.19	1.41	1.72	1.86	2.06	2.68	1.72	1.86	2.06	2.68	ns
LVC MOS15, QUIETIO, 2 mA	0.98	1.10	1.23	1.79	5.47	5.61	5.81	6.38	5.47	5.61	5.81	6.38	ns
LVC MOS15, QUIETIO, 4 mA	0.98	1.10	1.23	1.79	4.61	4.75	4.95	5.51	4.61	4.75	4.95	5.51	ns
LVC MOS15, QUIETIO, 6 mA	0.98	1.10	1.23	1.79	4.07	4.21	4.41	4.97	4.07	4.21	4.41	4.97	ns
LVC MOS15, QUIETIO, 8 mA	0.98	1.10	1.23	1.79	3.91	4.05	4.25	4.81	3.91	4.05	4.25	4.81	ns
LVC MOS15, QUIETIO, 12 mA	0.98	1.10	1.23	1.79	3.53	3.67	3.87	4.51	3.53	3.67	3.87	4.51	ns
LVC MOS15, QUIETIO, 16 mA	0.98	1.10	1.23	1.79	3.32	3.46	3.66	4.31	3.32	3.46	3.66	4.31	ns
LVC MOS15, Slow, 2 mA	0.98	1.10	1.23	1.79	4.18	4.32	4.52	5.11	4.18	4.32	4.52	5.11	ns
LVC MOS15, Slow, 4 mA	0.98	1.10	1.23	1.79	3.42	3.56	3.76	4.34	3.42	3.56	3.76	4.34	ns
LVC MOS15, Slow, 6 mA	0.98	1.10	1.23	1.79	2.29	2.43	2.63	3.24	2.29	2.43	2.63	3.24	ns

## I/O Standard Measurement Methodology

### Input Delay Measurements

Table 31 shows the test setup parameters used for measuring input delay.

Table 31: Input Delay Measurement Methodology

Description	I/O Standard Attribute	$V_L^{(1)}$	$V_H^{(1)}$	$V_{MEAS}^{(3)(4)}$	$V_{REF}^{(2)(4)}$
LVTTTL (Low-Voltage Transistor-Transistor Logic)	LVTTTL	0	3.0	1.4	–
LVC MOS (Low-Voltage CMOS), 3.3V	LVC MOS33	0	3.3	1.65	–
LVC MOS, 2.5V	LVC MOS25	0	2.5	1.25	–
LVC MOS, 1.8V	LVC MOS18	0	1.8	0.9	–
LVC MOS, 1.5V	LVC MOS15	0	1.5	0.75	–
LVC MOS, 1.2V	LVC MOS12	0	1.2	0.6	–
PCI (Peripheral Component Interface), 33 MHz and 66 MHz, 3.3V	PCI33_3, PCI66_3	Per PCI Specification			–
HSTL (High-Speed Transceiver Logic), Class I & II	HSTL_I, HSTL_II	$V_{REF} - 0.5$	$V_{REF} + 0.5$	$V_{REF}$	0.75
HSTL, Class III	HSTL_III	$V_{REF} - 0.5$	$V_{REF} + 0.5$	$V_{REF}$	0.90
HSTL, Class I & II, 1.8V	HSTL_I_18, HSTL_II_18	$V_{REF} - 0.5$	$V_{REF} + 0.5$	$V_{REF}$	0.90
HSTL, Class III 1.8V	HSTL_III_18	$V_{REF} - 0.5$	$V_{REF} + 0.5$	$V_{REF}$	1.1
SSTL (Stub Terminated Transceiver Logic), Class I & II, 3.3V	SSTL3_I, SSTL3_II	$V_{REF} - 0.75$	$V_{REF} + 0.75$	$V_{REF}$	1.5
SSTL, Class I & II, 2.5V	SSTL2_I, SSTL2_II	$V_{REF} - 0.75$	$V_{REF} + 0.75$	$V_{REF}$	1.25
SSTL, Class I & II, 1.8V	SSTL18_I, SSTL18_II	$V_{REF} - 0.5$	$V_{REF} + 0.5$	$V_{REF}$	0.90
SSTL, Class II, 1.5V	SSTL15_II	$V_{REF} - 0.2$	$V_{REF} + 0.2$	$V_{REF}$	0.75
LVDS (Low-Voltage Differential Signaling), 2.5V & 3.3V	LVDS_25, LVDS_33	$1.25 - 0.125$	$1.25 + 0.125$	0 <sup>(5)</sup>	–
LVPECL (Low-Voltage Positive Emitter-Coupled Logic), 2.5V & 3.3V	LVPECL_25, LVPECL_33	$1.2 - 0.3$	$1.2 + 0.3$	0 <sup>(5)</sup>	–
BLVDS (Bus LVDS), 2.5V	BLVDS_25	$1.3 - 0.125$	$1.3 + 0.125$	0 <sup>(5)</sup>	–
Mini-LVDS, 2.5V & 3.3V	MINI_LVDS_25, MINI_LVDS_33	$1.2 - 0.125$	$1.2 + 0.125$	0 <sup>(5)</sup>	–
RS DS (Reduced Swing Differential Signaling), 2.5V & 3.3V	RS DS_25, RS DS_33	$1.2 - 0.1$	$1.2 + 0.1$	0 <sup>(5)</sup>	–
TMDS (Transition Minimized Differential Signaling), 3.3V	TMDS_33	$3.0 - 0.1$	$3.0 + 0.1$	0 <sup>(5)</sup>	–
PPDS (Point-to-Point Differential Signaling), 2.5V & 3.3V	PPDS_25, PPDS_33	$1.25 - 0.1$	$1.25 + 0.1$	0 <sup>(5)</sup>	–

**Notes:**

1. Input waveform switches between  $V_L$  and  $V_H$ .
2. Measurements are made at typical, minimum, and maximum  $V_{REF}$  values. Reported delays reflect worst case of these measurements.  $V_{REF}$  values listed are typical.
3. Input voltage level from which measurement starts.
4. This is an input voltage reference that bears no relation to the  $V_{REF} / V_{MEAS}$  parameters found in IBIS models and/or noted in Figure 4.
5. The value given is the differential input voltage.

### Output Delay Measurements

Output delays are measured using a Tektronix P6245 TDS500/600 probe (< 1 pF) across approximately 4" of FR4 microstrip trace. Standard termination was used for all testing. The propagation delay of the 4" trace is characterized separately and subtracted from the final measurement, and is therefore not included in the generalized test setups shown in Figure 4 and Figure 5.

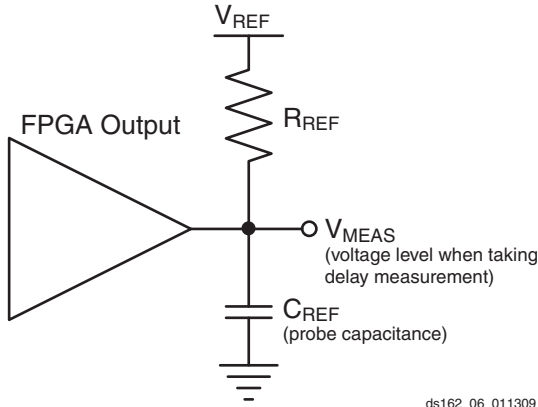
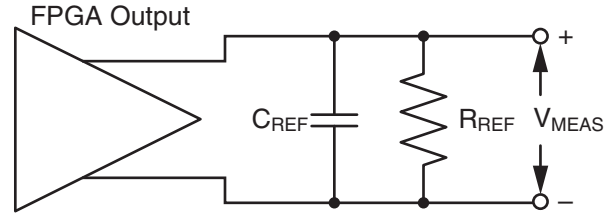


Figure 4: Single-Ended Test Setup



ds162\_07\_011309

Figure 5: Differential Test Setup

Measurements and test conditions are reflected in the IBIS models except where the IBIS format precludes it. Parameters  $V_{REF}$ ,  $R_{REF}$ ,  $C_{REF}$ , and  $V_{MEAS}$  fully describe the test conditions for each I/O standard. The most accurate prediction of propagation delay in any given application can be obtained through IBIS simulation, using the following method:

1. Simulate the output driver of choice into the generalized test setup, using values from Table 32.
2. Record the time to  $V_{MEAS}$ .
3. Simulate the output driver of choice into the actual PCB trace and load, using the appropriate IBIS model or capacitance value to represent the load.
4. Record the time to  $V_{MEAS}$ .
5. Compare the results of steps 2 and 4. The increase or decrease in delay yields the actual propagation delay of the PCB trace.

Table 32: Output Delay Measurement Methodology

Description	I/O Standard Attribute	$R_{REF}$ ( $\Omega$ )	$C_{REF}^{(1)}$ (pF)	$V_{MEAS}$ (V)	$V_{REF}$ (V)
LVTTTL (Low-Voltage Transistor-Transistor Logic)	LVTTTL (all)	1M	0	1.4	0
LVC MOS (Low-Voltage CMOS), 3.3V	LVC MOS33	1M	0	1.65	0
LVC MOS, 2.5V	LVC MOS25	1M	0	1.25	0
LVC MOS, 1.8V	LVC MOS18	1M	0	0.9	0
LVC MOS, 1.5V	LVC MOS15	1M	0	0.75	0
LVC MOS, 1.2V	LVC MOS12	1M	0	0.6	0
PCI (Peripheral Component Interface) 33 MHz and 66 MHz, 3.3V	PCI33_3, PCI66_3 (rising edge)	25	10 <sup>(2)</sup>	0.94	0
	PCI33_3, PCI66_3 (falling edge)	25	10 <sup>(2)</sup>	2.03	3.3
HSTL (High-Speed Transceiver Logic), Class I	HSTL_I	50	0	$V_{REF}$	0.75
HSTL, Class II	HSTL_II	25	0	$V_{REF}$	0.75
HSTL, Class III	HSTL_III	50	0	0.9	1.5
HSTL, Class I, 1.8V	HSTL_I_18	50	0	$V_{REF}$	0.9
HSTL, Class II, 1.8V	HSTL_II_18	25	0	$V_{REF}$	0.9
HSTL, Class III, 1.8V	HSTL_III_18	50	0	1.1	1.8
SSTL (Stub Series Terminated Logic), Class I, 1.8V	SSTL18_I	50	0	$V_{REF}$	0.9
SSTL, Class II, 1.8V	SSTL18_II	25	0	$V_{REF}$	0.9
SSTL, Class I, 2.5V	SSTL2_I	50	0	$V_{REF}$	1.25



Table 34: SSO Limit per V<sub>CC0</sub>/GND Pair (Cont'd)

V <sub>CC0</sub>	I/O Standard	Drive	Slew	SSO Limit per V <sub>CC0</sub> /GND Pair					
				All TQG144, CPG196, CSG225, FT(G)256, and LX devices in CSG324		All CS(G)484, FG(G)484, FG(G)676, FG(G)900, and LXT devices in CSG324			
				Bank 0/2	Bank 1/3	Bank 0/2	Bank 1/3/4/5		
3.3V	LVTTTL	2	Fast	53	65	53	62		
			Slow	70	80	70	73		
			QuietIO	79	89	79	91		
		4	Fast	23	30	23	27		
			Slow	34	41	34	37		
			QuietIO	44	49	44	46		
		6	Fast	16	21	16	20		
			Slow	21	28	21	25		
			QuietIO	34	39	34	34		
		8	Fast	12	16	12	15		
			Slow	16	22	16	19		
			QuietIO	27	28	27	24		
		12	Fast	1	3	1	1		
			Slow	2	5	2	4		
			QuietIO	2	10	2	8		
		16	Fast	1	3	1	1		
			Slow	1	7	1	2		
			QuietIO	3	11	3	8		
		24	Fast	1	2	1	1		
			Slow	2	5	2	2		
			QuietIO	8	9	8	8		
			PCI33_3			18	19	18	19
			PCI66_3			18	19	18	19
			SSTL_3_I			5	8	5	8
			SSTL_3_II			3	5	3	3
			DIFF_SSTL_3_I			15	24	15	24
			DIFF_SSTL_3_II			9	15	9	9
	SDIO			17	18	17	15		

## DSP48A1 Switching Characteristics

Table 44: DSP48A1 Switching Characteristics

Symbol	Description	Pre-adder	Multiplier	Post-adder	Speed Grade				Units
					-3	-3N	-2	-1L	
<b>Setup and Hold Times of Data/Control Pins to the Input Register Clock</b>									
$T_{DSPDCK\_A\_A1REG}/$ $T_{DSPCKD\_A\_A1REG}$	A input to A1 register CLK	N/A	N/A	N/A	0.15/ 0.09	0.17/ 0.09	0.17/ 0.09	0.32/ 0.09	ns
$T_{DSPDCK\_D\_B1REG}/$ $T_{DSPCKD\_D\_B1REG}$	D input to B1 register CLK	Yes	N/A	N/A	1.90/ -0.07	1.95/ -0.07	1.95/ -0.07	2.82/ -0.07	ns
$T_{DSPDCK\_C\_CREG}/$ $T_{DSPCKD\_C\_CREG}$	C input to C register CLK for XC devices	N/A	N/A	N/A	0.11/ 0.15	0.13/ 0.15	0.13/ 0.15	0.24/ 0.09	ns
	C input to C register CLK for XA and XQ devices				0.11/ 0.19	N/A	0.13/ 0.23	0.24/ 0.09	
$T_{DSPDCK\_D\_DREG}/$ $T_{DSPCKD\_D\_DREG}$	D input to D register CLK for XC devices	N/A	N/A	N/A	0.09/ 0.15	0.10/ 0.15	0.10/ 0.15	0.19/ 0.12	ns
	D input to D register CLK for XA and XQ devices				0.09/ 0.23	N/A	0.10/ 0.27	0.19/ 0.12	
$T_{DSPDCK\_OPMODE\_B1REG}/$ $T_{DSPCKD\_OPMODE\_B1REG}$	OPMODE input to B1 register CLK	Yes	N/A	N/A	1.97/ 0.01	2.00/ 0.01	2.00/ 0.01	2.85/ 0.01	ns
$T_{DSPDCK\_OPMODE\_OPMODEREG}/$ $T_{DSPCKD\_OPMODE\_OPMODEREG}$	OPMODE input to OPMODE register CLK for XC devices	N/A	N/A	N/A	0.18/ 0.12	0.21/ 0.12	0.21/ 0.12	0.40/ 0.12	ns
	OPMODE input to OPMODE register CLK for XA and XQ devices				0.18/ 0.16	N/A	0.21/ 0.22	0.40/ 0.12	
<b>Setup and Hold Times of Data Pins to the Pipeline Register Clock</b>									
$T_{DSPDCK\_A\_MREG}/$ $T_{DSPCKD\_A\_MREG}$	A input to M register CLK	N/A	Yes	N/A	3.06/ -0.40	3.51/ -0.40	3.51/ -0.40	3.97/ -0.40	ns
$T_{DSPDCK\_B\_MREG}/$ $T_{DSPCKD\_B\_MREG}$	B input to M register CLK	Yes	Yes	N/A	3.96/ -0.68	4.58/ -0.68	4.58/ -0.68	7.00/ -0.68	ns
$T_{DSPDCK\_D\_MREG}/$ $T_{DSPCKD\_D\_MREG}$	D input to M register CLK	Yes	Yes	N/A	4.23/ -0.56	4.80/ -0.56	4.80/ -0.56	6.84/ -0.56	ns
$T_{DSPDCK\_OPMODE\_MREG}/$ $T_{DSPCKD\_OPMODE\_MREG}$	OPMODE to M register CLK	Yes	Yes	N/A	4.18/ -0.48	4.80/ -0.48	4.80/ -0.48	6.88/ -0.48	ns
		No	Yes	N/A	2.37/ -0.48	2.70/ -0.48	2.70/ -0.48	4.28/ -0.48	ns
<b>Setup and Hold Times of Data/Control Pins to the Output Register Clock</b>									
$T_{DSPDCK\_A\_PREG}/$ $T_{DSPCKD\_A\_PREG}$	A input to P register CLK	N/A	Yes	Yes	4.32/ -0.76	5.06/ -0.76	5.06/ -0.76	7.52/ -0.76	ns
$T_{DSPDCK\_B\_PREG}/$ $T_{DSPCKD\_B\_PREG}$	B input to P register CLK	Yes	Yes	Yes	5.87/ -0.59	6.87/ -0.59	6.87/ -0.59	10.55/ -0.59	ns
		No	Yes	Yes	4.14/ -0.93	4.68/ -0.93	4.68/ -0.93	8.12/ -0.93	ns
$T_{DSPDCK\_C\_PREG}/$ $T_{DSPCKD\_C\_PREG}$	C input to P register CLK	N/A	N/A	Yes	2.20/ -0.23	2.25/ -0.23	2.25/ -0.23	3.27/ -0.23	ns
$T_{DSPDCK\_D\_PREG}/$ $T_{DSPCKD\_D\_PREG}$	D input to P register CLK	Yes	Yes	Yes	5.90/ -0.92	6.91/ -0.92	6.91/ -0.92	10.39/ -0.92	ns

## Configuration Switching Characteristics

Table 47: Configuration Switching Characteristics<sup>(1)</sup>

Symbol	Description	Speed Grade				Units
		-3	-3N	-2	-1L	
<b>Power-up Timing Characteristics</b>						
T <sub>PL</sub> <sup>(2)</sup>	PROGRAM_B Latency	4	4	4	5	ms, Max
T <sub>POR</sub> <sup>(2)</sup>	Power-on reset (50 ms ramp time) <sup>(3)</sup>	5/30	5/34	5/40	5/40	ms, Min/Max
	Power-on reset (10 ms ramp time)	5/25	5/29	5/35	5/40	ms, Min/Max
T <sub>PROGRAM</sub>	PROGRAM_B Pulse Width	500	500	500	500	ns, Min
<b>Slave Serial Mode Programming Switching</b>						
T <sub>DCCK</sub> /T <sub>CCKD</sub>	DIN Setup/Hold, slave mode	6.0/1.0	6.0/1.0	6.0/1.0	8.0/2.0	ns, Min
T <sub>CCO</sub>	CCLK to DOUT	12	12	12	17	ns, Max
F <sub>SCCK</sub>	Slave mode external CCLK	80	80	80	50	MHz, Max
<b>Slave SelectMAP Mode Programming Switching</b>						
T <sub>SMDCCK</sub> /T <sub>SMCCKD</sub>	SelectMAP Data Setup/Hold	6.0/1.0	6.0/1.0	6.0/1.0	8.0/2.0	ns, Min
T <sub>SMCSCCK</sub> /T <sub>SMCCKCS</sub>	CSI_B Setup/Hold	7.0/0.0	7.0/0.0	7.0/0.0	9.0/2.0	ns, Min
T <sub>SMWCCK</sub> /T <sub>SMCCKW</sub>	RDWR_B Setup/Hold	17.0/1.0	17.0/1.0	17.0/1.0	27.0/2.0	ns, Min
T <sub>SMCKCSO</sub>	CSO_B clock to out	16	16	16	26	ns, Max
T <sub>SMCO</sub>	CCLK to DATA out in readback	13	13	13	25	ns, Max
T <sub>SMCKBY</sub>	CCLK to BUSY out in readback	12	12	12	17	ns, Max
F <sub>SMCCK</sub>	Maximum CCLK frequency (LX4, LX9, LX16, LX25, LX25T, LX45, LX45T, LX75, and LX75T only)	50	50	50	25	MHz, Max
	Maximum CCLK frequency (LX100 and LX100T in x8 mode, LX150, and LX150T only)	40	40	40	20	MHz, Max
	Maximum CCLK frequency (LX100 and LX100T in x16 mode only)	35	35	35	20	MHz, Max
F <sub>RBCK</sub>	Maximum Readback CCLK frequency, including block RAM (LX4, LX9, LX16, LX25, LX25T, LX45, LX45T, LX75, and LX75T only)	20	20	20	4	MHz, Max
	Maximum Readback CCLK frequency, ignoring block RAM (POST_CRC) (LX4, LX9, LX16, LX25, LX25T, LX45, LX45T, LX75, and LX75T only)	50	50	50	30	MHz, Max
	Maximum Readback CCLK frequency, including block RAM (LX100, LX100T, LX150, and LX150T only)	12	12	12	4	MHz, Max
	Maximum Readback CCLK frequency, ignoring block RAM (POST_CRC) (LX100, LX100T, LX150, and LX150T only)	35	35	35	20	MHz, Max
<b>Boundary-Scan Port Timing Specifications</b>						
T <sub>TAPTCK</sub>	TMS and TDI Setup time before TCK	10	10	10	17	ns, Min
T <sub>TCKTAP</sub>	TMS and TDI Hold time after TCK	5.5	5.5	5.5	5.5	ns, Min
T <sub>TCKTDO</sub>	TCK falling edge to TDO output valid	6.5	6.5	6.5	8	ns, Max
T <sub>TCKH</sub>	TCK clock minimum High time	12	12	12	21	ns, Min
T <sub>TCKL</sub>	TCK clock minimum Low time	12	12	12	21	ns, Min
F <sub>TCK</sub>	Maximum configuration TCK clock frequency	33	33	33	18	MHz, Max
F <sub>TCKB</sub>	Maximum boundary-scan TCK clock frequency	33	33	33	18	MHz, Max
F <sub>TCKAES</sub>	Maximum AES key TCK clock frequency	2	2	2	2	MHz, Max

## Clock Buffers and Networks

Table 48: Global Clock Switching Characteristics (BUFGMUX)

Symbol	Description	Devices	Speed Grade				Units
			-3	-3N	-2	-1L	
T <sub>GSI</sub>	S pin Setup to I0/I1 inputs	LX devices	0.25	0.31	0.48	0.48	ns
		LXT devices	0.25	0.31	0.48	N/A	ns
T <sub>GIO</sub>	BUFGMUX delay from I0/I1 to O	LX devices	0.21	0.21	0.21	0.21	ns
		LXT devices	0.21	0.21	0.21	N/A	ns
<b>Maximum Frequency</b>							
F <sub>MAX</sub>	Global clock tree (BUFGMUX)	LX devices	400	400	375	250	MHz
		LXT devices	400	400	375	N/A	MHz

Table 49: Input/Output Clock Switching Characteristics (BUFIO2)

Symbol	Description	Devices	Speed Grade				Units
			-3	-3N	-2	-1L	
T <sub>BUFCO_O</sub>	Clock to out delay from I to O	LX devices	0.67	0.82	1.09	1.50	ns
		LXT devices	0.67	0.82	1.09	N/A	ns
<b>Maximum Frequency</b>							
F <sub>MAX</sub>	I/O clock tree (BUFIO2)	LX devices	540	525	500	300	MHz
		LXT devices	540	525	500	N/A	MHz

Table 50: Input/Output Clock Switching Characteristics (BUFIO2FB)

Symbol	Description	Devices	Speed Grade				Units
			-3	-3N	-2	-1L	
<b>Maximum Frequency</b>							
F <sub>MAX</sub>	I/O clock tree (BUFIO2FB)	LX devices	1080	1050	950	500	MHz
		LXT devices	1080	1050	950	N/A	MHz

Table 51: Input/Output Clock Switching Characteristics (BUFPLL)

Symbol	Description	Devices	Speed Grade				Units
			-3	-3N	-2	-1L	
<b>Maximum Frequency</b>							
F <sub>MAX</sub>	BUFPLL clock tree (BUFPLL)	LX devices	1080	1050	950	500	MHz
		LXT devices	1080	1050	950	N/A	MHz

## PLL Switching Characteristics

Table 52: PLL Specification

Symbol	Description	Device <sup>(1)</sup>	Speed Grade				Units
			-3	-3N	-2	-1L	
F <sub>INMAX</sub>	Maximum Input Clock Frequency from I/O Clock	LX devices	540	525	450	300	MHz
		LXT devices	540	525	450	N/A	MHz
	Maximum Input Clock Frequency from Global Clock	LX devices	400	400	375	250	MHz
		LXT devices	400	400	375	N/A	MHz

Table 52: PLL Specification (Cont'd)

Symbol	Description	Device <sup>(1)</sup>	Speed Grade				Units
			-3	-3N	-2	-1L	
F <sub>INMIN</sub>	Minimum Input Clock Frequency	LX devices	19	19	19	19	MHz
		LXT devices	19	19	19	N/A	MHz
F <sub>INJITTER</sub>	Maximum Input Clock Period Jitter: 19–200 MHz	All	1 ns Maximum				
	Maximum Input Clock Period Jitter: > 200 MHz	All	<20% of clock input period Maximum				
F <sub>INDUTY</sub>	Allowable Input Duty Cycle: 19—199 MHz	All	25/75				%
	Allowable Input Duty Cycle: 200—299 MHz	All	35/65				%
	Allowable Input Duty Cycle: > 300 MHz	All	45/55				%
F <sub>VCOMIN</sub>	Minimum PLL VCO Frequency	LX devices	400	400	400	400	MHz
		LXT devices	400	400	400	N/A	MHz
F <sub>VCOMAX</sub>	Maximum PLL VCO Frequency	LX devices	1080	1050	1000	1000	MHz
		LXT devices	1080	1050	1000	N/A	MHz
F <sub>BANDWIDTH</sub>	Low PLL Bandwidth at Typical <sup>(3)</sup>	All	1	1	1	1	MHz
	High PLL Bandwidth at Typical <sup>(3)</sup>	All	4	4	4	4	MHz
T <sub>STAPHAOFFSET</sub>	Static Phase Offset of the PLL Outputs	All	0.12	0.12	0.12	0.15	ns
T <sub>OUTJITTER</sub>	PLL Output Jitter <sup>(3)</sup>	All	Note 2				
T <sub>OUTDUTY</sub>	PLL Output Clock Duty Cycle Precision <sup>(4)</sup>	All	0.15	0.15	0.20	0.25	ns
T <sub>LOCKMAX</sub>	PLL Maximum Lock Time	All	100	100	100	100	µs
F <sub>OUTMAX</sub>	PLL Maximum Output Frequency for BUFGMUX	LX devices	400	400	375	250	MHz
		LXT devices	400	400	375	N/A	MHz
	PLL Maximum Output Frequency for BUFPLL	LX devices	1080	1050	950	500	MHz
		LXT devices	1080	1050	950	N/A	MHz
F <sub>OUTMIN</sub>	PLL Minimum Output Frequency <sup>(5)</sup>	All	3.125	3.125	3.125	3.125	MHz
T <sub>EXTFDVAR</sub>	External Clock Feedback Variation: 19–200 MHz	All	1 ns Maximum				
	External Clock Feedback Variation: > 200 MHz	All	< 20% of clock input period Maximum				
RST <sub>MINPULSE</sub>	Minimum Reset Pulse Width	All	5	5	5	5	ns
F <sub>PFDMAX</sub> <sup>(5)</sup>	Maximum Frequency at the Phase Frequency Detector	LX devices	500	500	400	300	MHz
		LXT devices	500	500	400	N/A	MHz
F <sub>PFDMIN</sub>	Minimum Frequency at the Phase Frequency Detector	LX devices	19	19	19	19	MHz
		LXT devices	19	19	19	N/A	MHz
T <sub>FBDELAY</sub>	Maximum Delay in the Feedback Path	All	3 ns Max or one CLKIN cycle				

**Notes:**

1. LXT devices are not available with a -1L speed grade.
2. Values for this parameter are available in the Clocking Wizard.
3. The PLL does not filter typical spread spectrum input clocks because they are usually far below the bandwidth filter frequencies.
4. Includes global clock buffer.
5. Calculated as  $F_{VCO}/128$  assuming output duty cycle is 50%.
6. When using  $CLK\_FEEDBACK = CLKOUT0$  with  $BUFIO2$  feedback, the feedback frequency will be higher than the phase frequency detector frequency.  $F_{PFDMAX} = F_{CLKFB} / CLKFBOUT\_MULT$

Table 59: Switching Characteristics for the Phase-Shift Clock in Variable Phase Mode<sup>(1)</sup>

Symbol	Description	Amount of Phase Shift	Units
<b>Phase Shifting Range</b>			
MAX_STEPS <sup>(2)</sup>	When CLKIN < 60 MHz, the maximum allowed number of DCM_DELAY_STEP steps for a given CLKIN clock period, where T = CLKIN clock period in ns. When using CLKIN_DIVIDE_BY_2 = TRUE, double the clock-effective clock period.	$\pm(\text{INTEGER}(10 \times (\text{TCLKIN} - 3 \text{ ns})))$	steps
	When CLKIN ≥ 60 MHz, the maximum allowed number of DCM_DELAY_STEP steps for a given CLKIN clock period, where T = CLKIN clock period in ns. When using CLKIN_DIVIDE_BY_2 = TRUE, double the clock-effective clock period.	$\pm(\text{INTEGER}(15 \times (\text{TCLKIN} - 3 \text{ ns})))$	steps
FINE_SHIFT_RANGE_MIN	Minimum guaranteed delay for variable phase shifting.	$\pm(\text{MAX\_STEPS} \times \text{DCM\_DELAY\_STEP\_MIN})$	ps
FINE_SHIFT_RANGE_MAX	Maximum guaranteed delay for variable phase shifting	$\pm(\text{MAX\_STEPS} \times \text{DCM\_DELAY\_STEP\_MAX})$	ps

**Notes:**

1. The values in this table are based on the operating conditions described in Table 53 and Table 58.
2. The maximum variable phase shift range, MAX\_STEPS, is only valid when the DCM has no initial fixed-phase shifting, that is, the PHASE\_SHIFT attribute is set to 0.
3. The DCM\_DELAY\_STEP values are provided at the end of Table 54.

Table 60: Miscellaneous DCM Timing Parameters<sup>(1)</sup>

Symbol	Description	Min	Max	Units
DCM_RST_PW_MIN	Minimum duration of a RST pulse width	3	–	CLKIN cycles

**Notes:**

1. This limit only applies to applications that use the DCM DLL outputs (CLK0, CLK90, CLK180, CLK270, CLK2X, CLK2X180, and CLKDV). The DCM DFS outputs (CLKFX, CLKFXDV, CLKFX180) are unaffected.

Table 61: Frequency Synthesis

Attribute	Min	Max
CLKFX_MULTIPLY (DCM_SP)	2	32
CLKFX_DIVIDE (DCM_SP)	1	32
CLKDV_DIVIDE (DCM_SP)	1.5	16
CLKFX_MULTIPLY (DCM_CLKGEN)	2	256
CLKFX_DIVIDE (DCM_CLKGEN)	1	256
CLKFXDV_DIVIDE (DCM_CLKGEN)	2	32

Table 62: DCM Switching Characteristics

Symbol	Description	Speed Grade				Units
		-3	-3N	-2	-1L	
T <sub>DMCKC_PSEN</sub> /T <sub>DMCKC_PSEN</sub>	PSEN Setup/Hold	1.50/ 0.00	1.50/ 0.00	1.50/ 0.00	1.50/ 0.00	ns
T <sub>DMCKC_PSINCDEC</sub> /T <sub>DMCKC_PSINCDEC</sub>	PSINCDEC Setup/Hold	1.50/ 0.00	1.50/ 0.00	1.50/ 0.00	1.50/ 0.00	ns
T <sub>DMCKO_PSDONE</sub>	Clock to out of PSDONE	1.50	1.50	1.50	1.50	ns

## Spartan-6 Device Pin-to-Pin Output Parameter Guidelines

All devices are 100% functionally tested. The representative values for typical pin locations and normal clock loading are listed in Table 63 through Table 69. Values are expressed in nanoseconds unless otherwise noted.

Table 63: Global Clock Input to Output Delay Without DCM or PLL

Symbol	Description	Device	Speed Grade				Units
			-3	-3N	-2	-1L	
LVCMOS25 Global Clock Input to Output Delay using Output Flip-Flop, 12mA, Fast Slew Rate, <i>without</i> DCM or PLL							
T <sub>ICKOF</sub>	Global Clock and OUTFF <i>without</i> DCM or PLL	XC6SLX4	6.12	N/A	7.68	9.41	ns
		XC6SLX9	6.12	6.51	7.68	9.41	ns
		XC6SLX16	5.98	6.42	7.48	9.10	ns
		XC6SLX25	6.20	6.69	7.84	9.44	ns
		XC6SLX25T	6.20	6.69	7.84	N/A	ns
		XC6SLX45	6.37	6.88	8.10	9.61	ns
		XC6SLX45T	6.37	6.88	8.10	N/A	ns
		XC6SLX75	6.39	6.99	8.16	10.18	ns
		XC6SLX75T	6.39	6.99	8.16	N/A	ns
		XC6SLX100	6.59	7.18	8.41	10.31	ns
		XC6SLX100T	6.59	7.18	8.41	N/A	ns
		XC6SLX150	6.98	7.68	8.80	10.62	ns
		XC6SLX150T	6.98	7.68	8.80	N/A	ns
		XA6SLX4	6.44	N/A	7.68	N/A	ns
		XA6SLX9	6.44	N/A	7.68	N/A	ns
		XA6SLX16	6.30	N/A	7.48	N/A	ns
		XA6SLX25	6.52	N/A	7.84	N/A	ns
		XA6SLX25T	6.52	N/A	7.84	N/A	ns
		XA6SLX45	6.69	N/A	8.12	N/A	ns
		XA6SLX45T	6.69	N/A	8.12	N/A	ns
		XA6SLX75	6.89	N/A	8.16	N/A	ns
		XA6SLX75T	6.89	N/A	8.16	N/A	ns
		XA6SLX100	N/A	N/A	8.36	N/A	ns
XQ6SLX75	N/A	N/A	8.16	10.18	ns		
XQ6SLX75T	6.89	N/A	8.16	N/A	ns		
XQ6SLX150	N/A	N/A	8.80	10.62	ns		
XQ6SLX150T	7.61	N/A	8.80	N/A	ns		

**Notes:**

- Listed above are representative values where one global clock input drives one vertical clock line in each accessible column, and where all accessible IOB and CLB flip-flops are clocked by the global clock net.

Table 64: Global Clock Input to Output Delay With DCM in System-Synchronous Mode

Symbol	Description	Device	Speed Grade				Units
			-3	-3N	-2	-1L	
LVCMOS25 Global Clock Input to Output Delay using Output Flip-Flop, 12mA, Fast Slew Rate, with DCM in System-Synchronous Mode.							
T <sub>ICKOFDCM</sub>	Global Clock and OUTFF with DCM	XC6SLX4	4.23	N/A	6.11	6.60	ns
		XC6SLX9	4.23	5.17	6.11	6.60	ns
		XC6SLX16	4.28	4.57	5.34	6.36	ns
		XC6SLX25	3.95	4.18	4.59	6.91	ns
		XC6SLX25T	3.95	4.18	4.59	N/A	ns
		XC6SLX45	4.37	4.70	5.50	6.85	ns
		XC6SLX45T	4.37	4.70	5.50	N/A	ns
		XC6SLX75	3.90	4.23	4.77	6.31	ns
		XC6SLX75T	3.90	4.23	4.77	N/A	ns
		XC6SLX100	3.86	4.16	4.66	7.25	ns
		XC6SLX100T	3.90	4.16	4.66	N/A	ns
		XC6SLX150	4.03	4.33	4.83	6.63	ns
		XC6SLX150T	4.03	4.33	4.83	N/A	ns
		XA6SLX4	4.55	N/A	6.11	N/A	ns
		XA6SLX9	4.55	N/A	6.11	N/A	ns
		XA6SLX16	4.62	N/A	5.33	N/A	ns
		XA6SLX25	4.27	N/A	4.59	N/A	ns
		XA6SLX25T	4.27	N/A	4.69	N/A	ns
		XA6SLX45	4.69	N/A	5.50	N/A	ns
		XA6SLX45T	4.69	N/A	5.50	N/A	ns
		XA6SLX75	4.22	N/A	4.77	N/A	ns
		XA6SLX75T	4.22	N/A	4.77	N/A	ns
		XA6SLX100	N/A	N/A	5.34	N/A	ns
		XQ6SLX75	N/A	N/A	4.77	6.31	ns
		XQ6SLX75T	4.22	N/A	4.77	N/A	ns
		XQ6SLX150	N/A	N/A	4.96	6.63	ns
		XQ6SLX150T	4.62	N/A	4.96	N/A	ns

Notes:

1. Listed above are representative values where one global clock input drives one vertical clock line in each accessible column, and where all accessible IOB and CLB flip-flops are clocked by the global clock net.
2. DCM output jitter is already included in the timing calculation.



**Table 67: Global Clock Input to Output Delay With PLL in Source-Synchronous Mode**

Symbol	Description	Device	Speed Grade				Units
			-3	-3N	-2	-1L	
LVCMOS25 Global Clock Input to Output Delay using Output Flip-Flop, 12mA, Fast Slew Rate, <i>with</i> PLL in Source-Synchronous Mode.							
T <sub>ICKOFFLL_0</sub>	Global Clock and OUTFF <i>with</i> PLL	XC6SLX4	5.49	N/A	7.44	8.55	ns
		XC6SLX9	5.49	6.29	7.44	8.55	ns
		XC6SLX16	5.23	5.77	6.79	8.21	ns
		XC6SLX25	5.00	5.35	6.10	8.54	ns
		XC6SLX25T	5.00	5.35	6.10	N/A	ns
		XC6SLX45	5.59	6.03	7.02	8.39	ns
		XC6SLX45T	5.59	6.03	7.02	N/A	ns
		XC6SLX75	4.96	5.41	6.22	8.32	ns
		XC6SLX75T	4.96	5.41	6.22	N/A	ns
		XC6SLX100	4.97	5.42	6.21	9.08	ns
		XC6SLX100T	5.01	5.42	6.21	N/A	ns
		XC6SLX150	4.59	5.06	5.86	8.13	ns
		XC6SLX150T	4.59	5.06	5.86	N/A	ns
		XA6SLX4	5.79	N/A	7.32	N/A	ns
		XA6SLX9	5.79	N/A	7.32	N/A	ns
		XA6SLX16	5.56	N/A	6.66	N/A	ns
		XA6SLX25	5.40	N/A	5.97	N/A	ns
		XA6SLX25T	5.40	N/A	6.07	N/A	ns
		XA6SLX45	5.89	N/A	6.90	N/A	ns
		XA6SLX45T	5.89	N/A	6.90	N/A	ns
		XA6SLX75	5.27	N/A	6.12	N/A	ns
		XA6SLX75T	5.27	N/A	6.12	N/A	ns
		XA6SLX100	N/A	N/A	6.80	N/A	ns
		XQ6SLX75	N/A	N/A	6.12	8.32	ns
		XQ6SLX75T	5.27	N/A	6.12	N/A	ns
		XQ6SLX150	N/A	N/A	5.88	8.13	ns
		XQ6SLX150T	5.21	N/A	5.88	N/A	ns

**Notes:**

1. Listed above are representative values where one global clock input drives one vertical clock line in each accessible column, and where all accessible IOB and CLB flip-flops are clocked by the global clock net.
2. PLL output jitter is included in the timing calculation.

Table 76: Global Clock Setup and Hold With DCM and PLL in System-Synchronous Mode

Symbol	Description	Device	Speed Grade				Units
			-3	-3N	-2	-1L	
<b>Input Setup and Hold Time Relative to Global Clock Input Signal for LVC MOS25 Standard.<sup>(1)</sup></b>							
T <sub>PSDCMPLL</sub> / T <sub>PHDCMPLL</sub>	No Delay Global Clock and IFF <sup>(2)</sup> with DCM in System-Synchronous Mode and PLL in DCM2PLL Mode.	XC6SLX4	1.16/0.49	N/A	1.39/0.49	2.36/0.59	ns
		XC6SLX9	1.16/0.44	1.37/0.44	1.39/0.44	2.36/0.59	ns
		XC6SLX16	1.44/-0.08	1.49/-0.04	1.62/-0.04	2.06/0.55	ns
		XC6SLX25	1.52/0.42	1.65/0.42	1.83/0.42	2.52/0.43	ns
		XC6SLX25T	1.52/0.42	1.65/0.42	1.83/0.42	N/A	ns
		XC6SLX45	1.54/0.39	1.59/0.39	1.75/0.39	2.48/0.76	ns
		XC6SLX45T	1.54/0.39	1.59/0.39	1.75/0.39	N/A	ns
		XC6SLX75	1.72/0.41	1.80/0.41	1.99/0.41	2.60/0.75	ns
		XC6SLX75T	1.72/0.41	1.80/0.41	1.99/0.41	N/A	ns
		XC6SLX100	1.34/0.51	1.46/0.51	1.64/0.51	2.12/0.90	ns
		XC6SLX100T	1.34/0.51	1.46/0.51	1.64/0.51	N/A	ns
		XC6SLX150	1.30/0.60	1.40/0.60	1.55/0.60	2.57/0.97	ns
		XC6SLX150T	1.30/0.60	1.40/0.60	1.55/0.60	N/A	ns
		XA6SLX4	1.58/0.37	N/A	1.58/0.37	N/A	ns
		XA6SLX9	1.58/0.37	N/A	1.58/0.37	N/A	ns
		XA6SLX16	2.67/0.35	N/A	2.67/0.17	N/A	ns
		XA6SLX25	1.74/0.27	N/A	1.95/0.27	N/A	ns
		XA6SLX25T	1.74/0.27	N/A	2.03/0.27	N/A	ns
		XA6SLX45	1.58/0.29	N/A	1.87/0.29	N/A	ns
		XA6SLX45T	1.58/0.29	N/A	1.87/0.29	N/A	ns
		XA6SLX75	1.74/0.24	N/A	2.11/0.24	N/A	ns
		XA6SLX75T	1.74/0.24	N/A	2.11/0.24	N/A	ns
		XA6SLX100	N/A	N/A	2.64/0.82	N/A	ns
		XQ6SLX75	N/A	N/A	2.11/0.24	2.60/0.75	ns
		XQ6SLX75T	1.74/0.24	N/A	2.11/0.24	N/A	ns
		XQ6SLX150	N/A	N/A	1.67/0.70	2.57/0.97	ns
XQ6SLX150T	1.50/0.70	N/A	1.67/0.70	N/A	ns		

**Notes:**

1. Setup and Hold times are measured over worst case conditions (process, voltage, temperature). Setup time is measured relative to the Global Clock input signal using the slowest process, highest temperature, and lowest voltage. Hold time is measured relative to the Global Clock input signal using the fastest process, lowest temperature, and highest voltage. These measurements include CMT jitter; DCM CLK0 driving PLL, PLL CLKOUT0 driving BUFG.
2. IFF = Input Flip-Flop or Latch
3. Use IBIS to determine any duty-cycle distortion incurred using various standards.

## Source-Synchronous Switching Characteristics

The parameters in this section provide the necessary values for calculating timing budgets for Spartan-6 FPGA source-synchronous transmitter and receiver data-valid windows.

Table 78: Duty Cycle Distortion and Clock-Tree Skew

Symbol	Description	Device <sup>(1)</sup>	Speed Grade				Units
			-3	-3N	-2	-1L	
T <sub>DCD_CLK</sub>	Global Clock Tree Duty Cycle Distortion <sup>(2)</sup>	LX4	0.20	N/A	0.20	0.35	ns
		LX9	0.20	0.20	0.20	0.35	ns
		LX16	0.20	0.20	0.20	0.35	ns
		LX25	0.20	0.20	0.20	0.35	ns
		LX25T	0.20	0.20	0.20	N/A	ns
		LX45	0.20	0.20	0.20	0.35	ns
		LX45T	0.20	0.20	0.20	N/A	ns
		LX75	0.20	0.20	0.20	0.35	ns
		LX75T	0.20	0.20	0.20	N/A	ns
		LX100	0.20	0.20	0.20	0.35	ns
		LX100T	0.20	0.20	0.20	N/A	ns
		LX150	0.35	0.35	0.35	0.35	ns
		LX150T	0.35	0.35	0.35	N/A	ns
		T <sub>CKSKEW</sub>	Global Clock Tree Skew <sup>(3)</sup>	LX4	0.25	N/A	0.25
LX9	0.25			0.25	0.25	0.29	ns
LX16	0.15			0.15	0.15	0.22	ns
LX25	0.26			0.26	0.26	0.41	ns
LX25T	0.26			0.26	0.26	N/A	ns
LX45	0.20			0.20	0.20	0.28	ns
LX45T	0.20			0.20	0.20	N/A	ns
LX75	0.56			0.56	0.56	0.50	ns
LX75T	0.56			0.56	0.56	N/A	ns
XC6SLX100 <sup>(4)</sup>	0.22			0.22	0.22	0.21	ns
XA6SLX100 <sup>(4)</sup>	N/A			N/A	0.43	N/A	ns
LX100T	0.22			0.22	0.22	N/A	ns
LX150	0.48			0.48	0.48	0.35	ns
LX150T	0.48			0.48	0.48	N/A	ns
T <sub>DCD_BUFIO2</sub>	I/O clock tree duty cycle distortion	LX devices	0.25	0.25	0.25	0.50	ns
		LXT devices	0.25	0.25	0.25	N/A	ns

Table 81: Source-Synchronous Pin-to-Pin Setup/Hold and Clock-to-Out Using BUFIO2

Symbol	Description	Device	Speed Grade				Units
			-3	-3N	-2	-1L	
<b>Data Input Setup and Hold Times Relative to a Forwarded Clock Input Pin Using BUFIO2</b>							
T <sub>PSCS</sub> /T <sub>PHCS</sub>	IFF setup/hold using BUFIO2 clock	XC6SLX4	0.57/0.94	N/A	0.95/1.12	0.27/1.56	ns
		XC6SLX9	0.40/0.95	0.50/0.96	0.60/1.12	0.27/1.56	ns
		XC6SLX16	0.48/0.74	0.55/0.75	0.69/0.83	1.27/1.31	ns
		XC6SLX25	0.28/1.02	0.28/1.12	0.28/1.24	0.15/1.78	ns
		XC6SLX25T	0.28/1.02	0.28/1.12	0.28/1.24	N/A	ns
		XC6SLX45	0.42/1.19	0.44/1.29	0.50/1.40	0.12/1.83	ns
		XC6SLX45T	0.42/1.19	0.44/1.29	0.50/1.40	N/A	ns
		XC6SLX75	0.38/1.48	0.38/1.63	0.38/1.84	0.05/2.78	ns
		XC6SLX75T	0.38/1.48	0.38/1.63	0.38/1.84	N/A	ns
		XC6SLX100	0.06/1.48	0.06/1.63	0.06/1.87	-0.03/2.72	ns
		XC6SLX100T	0.06/1.48	0.06/1.63	0.06/1.87	N/A	ns
		XC6SLX150	0.04/1.73	0.04/1.75	0.04/1.98	-0.08/3.07	ns
		XC6SLX150T	0.04/1.73	0.04/1.75	0.04/1.98	N/A	ns
		XA6SLX4	0.64/0.96	N/A	0.97/1.12	N/A	ns
		XA6SLX9	0.44/0.99	N/A	0.62/1.16	N/A	ns
		XA6SLX16	0.50/0.78	N/A	0.69/0.83	N/A	ns
		XA6SLX25	0.28/1.04	N/A	0.28/1.25	N/A	ns
		XA6SLX25T	0.28/1.04	N/A	0.28/1.25	N/A	ns
		XA6SLX45	0.43/1.21	N/A	0.50/1.40	N/A	ns
		XA6SLX45T	0.43/1.21	N/A	0.50/1.40	N/A	ns
		XA6SLX75	0.38/1.49	N/A	0.38/1.84	N/A	ns
		XA6SLX75T	0.38/1.49	N/A	0.38/1.84	N/A	ns
		XA6SLX100	N/A	N/A	1.01/1.63	N/A	ns
		XQ6SLX75	N/A	N/A	0.38/1.84	0.05/2.78	ns
		XQ6SLX75T	0.38/1.49	N/A	0.38/1.84	N/A	ns
		XQ6SLX150	N/A	N/A	0.04/1.98	-0.08/3.07	ns
		XQ6SLX150T	0.04/1.75	N/A	0.04/1.98	N/A	ns

Date	Version	Description of Revisions
09/14/11	2.4	<p>Production release of the XA6SLX4 and XA6SLX9 devices in <a href="#">Table 26</a> and <a href="#">Table 27</a> using ISE v13.2 software with -2 and -3 speed specification v1.19. Added production released version of the XA6SLX100 to <a href="#">Table 26</a> and <a href="#">Table 27</a> using ISE v13.3 software with -2 speed specification v1.20.</p> <p>Updated <math>R_{OUT\_TERM}</math> description in <a href="#">Table 4</a>. Fixed the LVPECL <math>V_H</math> error in <a href="#">Table 31</a>. Updated introduction in <a href="#">Simultaneously Switching Outputs</a>. Added the XA6SLX100 to <a href="#">Table 63</a> through <a href="#">Table 78</a>, and <a href="#">Table 81</a>. Added <a href="#">Note 4</a> to <a href="#">Table 78</a> because the <math>T_{CKSKREW}</math> for the XC6SLX100 is not the same as the <math>T_{CKSKREW}</math> for the XA6SLX100.</p> <p>Revised the revision history for version 1.6 dated <a href="#">06/24/10</a>. Removed the parenthetical statement about the -3N speed grade: (specifications are identical to the -3 speed grade).</p>
10/17/11	3.0	<p>Changed the data sheet from Preliminary Product Specification to Product Specification.</p> <p>Updated the <a href="#">Switching Characteristics, page 19</a> speed specification version ISE v13.3 software to -2 and -3 speed specification v1.20 and -1L speed specification of v1.08. Also updated <a href="#">Note 1</a> in <a href="#">Table 27</a>.</p> <p>In <a href="#">Table 43</a>, <i>Block RAM Switching Characteristics</i>, the <math>F_{MAX}</math> value for the -2 speed grade has been changed from 260 MHz to 280 MHz.</p> <p>In <a href="#">Table 54</a>, <i>Switching Characteristics for the DLL</i>, a <a href="#">Note 6</a> was added and linked to <code>CLKIN_CLKFB_PHASE</code>.</p>